PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KUO-MING WU	08/15/2018
CHING-CHUN WANG	08/15/2018
DUN-NIAN YAUNG	08/15/2018
HSING-CHIH LIN	08/15/2018
JEN-CHENG LIU	08/15/2018
MIN-FENG KAO	08/15/2018
YUNG-LUNG LIN	08/15/2018
SHIH-HAN HUANG	08/15/2018
I-NAN CHEN	08/15/2018

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16902539

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DATE SIGNED:	06/16/2020

Total Attachments: 12
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TSMC Docket No. P20173994US00
Docket No. TSMCP893US

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):
Kuo-Ming Wu

Assignor(s):
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Assignor(s):
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Assignor(s):
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AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled **"HYBRID BONDING TECHNOLOGY FOR STACKING INTEGRATED CIRCUITS"** for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. ______________________,
filed on ______________________.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2018. 08. 15
Date

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2018/08/15
Date

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Date

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